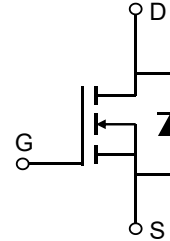


Description

Features

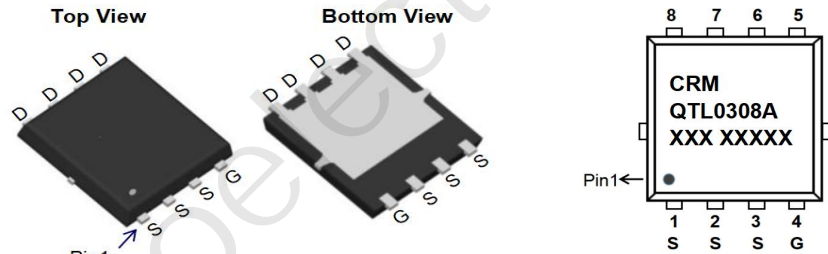
- 30V, 30A
 $R_{DS(ON)} \text{ Typ} = 6.2\text{m}\Omega @ V_{GS} = 10\text{V}$
 $R_{DS(ON)} \text{ Typ} = 11\text{m}\Omega @ V_{GS} = 4.5\text{V}$
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- 100% UIS TESTED!
- 100% ΔV_{ds} TESTED!



Schematic Diagram

Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMQTL0308A	CRMQTL0308A	PDFN3.3x3.3-8L	TAPING	13"	5000	50000

Absolute Maximum Ratings (@ $T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Units	
V _{DS}	Drain-to-Source Voltage	30	V	
V _{GS}	Gate-to-Source Voltage	±20	V	
I _D	Continuous Drain Current	T _C = 25°C	30	A
		T _C = 100°C	24	A
I _{DM}	Pulsed Drain Current ⁽¹⁾	120	A	
E _{AS}	Single Pulsed Avalanche Energy ⁽²⁾	39	mJ	
P _D	Power Dissipation	T _C = 25°C	13.9	W
R _{θJC}	Thermal Resistance, Junction to Case	9	°C/W	
T _J , T _{STG}	Junction & Storage Temperature Range	-55 to 150	°C	

Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
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Off Characteristics

V _{(BR)DSS}	Drain-Source Breakdown Voltage	I _D = 250μA, V _{GS} = 0V	30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 30V, V _{GS} = 0V	-	-	1.0	μA
I _{GSS}	Gate-Body Leakage Current	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	1	1.6	2.5	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽³⁾	V _{GS} = 10V, I _D = 25A	-	6.2	8.1	mΩ
		V _{GS} = 4.5V, I _D = 15A	-	11	14.3	mΩ

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{GS} = 0V, V _{DS} = 15V, f = 1MHz	-	1310	-	pF
C _{oss}	Output Capacitance		-	180	-	pF
C _{rss}	Reverse Transfer Capacitance		-	136	-	pF
Q _g	Total Gate Charge	V _{GS} = 0 to 10V V _{DS} = 15V, I _D = 20A	-	23	-	nC
Q _{gs}	Gate Source Charge		-	4.5	-	nC
Q _{gd}	Gate Drain("Miller") Charge		-	5.5	-	nC

Switching Characteristics

t _{d(on)}	Turn-On DelayTime	V _{GS} = 10V, V _{DD} = 15V I _D = 15A, R _{GEN} = 3Ω	-	7	-	ns
t _r	Turn-On Rise Time		-	15	-	ns
t _{d(off)}	Turn-Off DelayTime		-	25	-	ns
t _f	Turn-Off Fall Time		-	6	-	ns

Drain-Source Diode Characteristics and Max Ratings

I _S	Maximum Continuous Drain to Source Diode Forward Current	V _{GS} = 0V, I _S = 15A	-	-	30	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	120	A
V _{SD}	Drain to Source Diode Forward Voltage		-	-	1.2	V
t _{rr}	Body Diode Reverse Recovery Time		-	10	-	ns
Q _{rr}	Body Diode Reverse Recovery Charge		-	3	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
 2. E_{AS} condition: Starting T_J=25°C, V_{DD}=15V, V_G=10V, R_G=25ohm, L=0.5mH, I_{AS}=12.5A
 3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%.

Typical Performance Characteristics

Figure 1: Output Characteristics

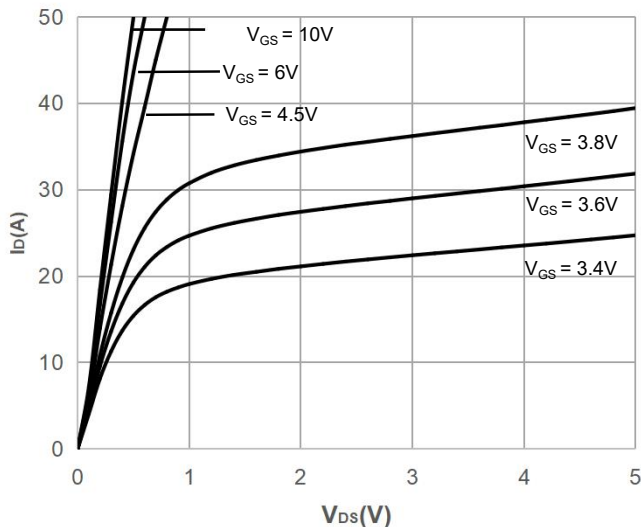


Figure 2: Typical Transfer Characteristics

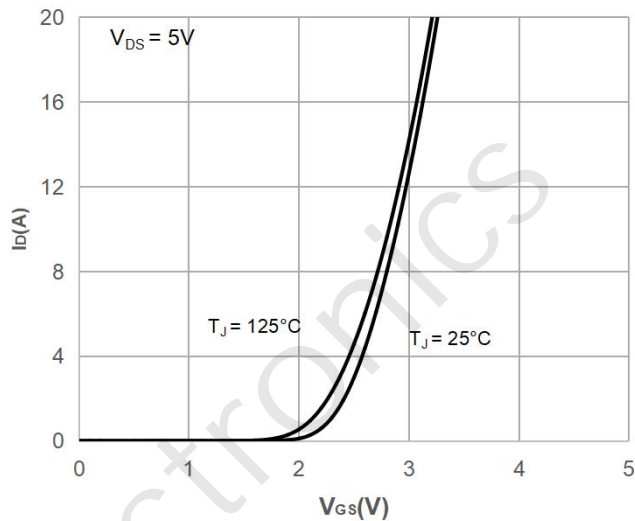


Figure 3: On-resistance vs. Drain Current

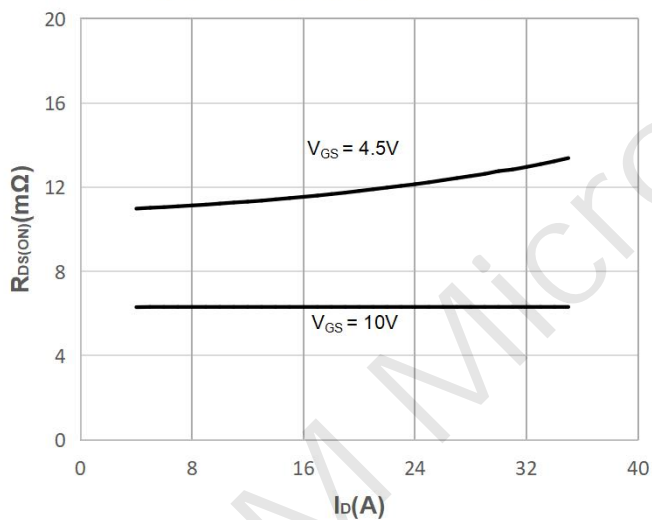


Figure 4: Body Diode Characteristics

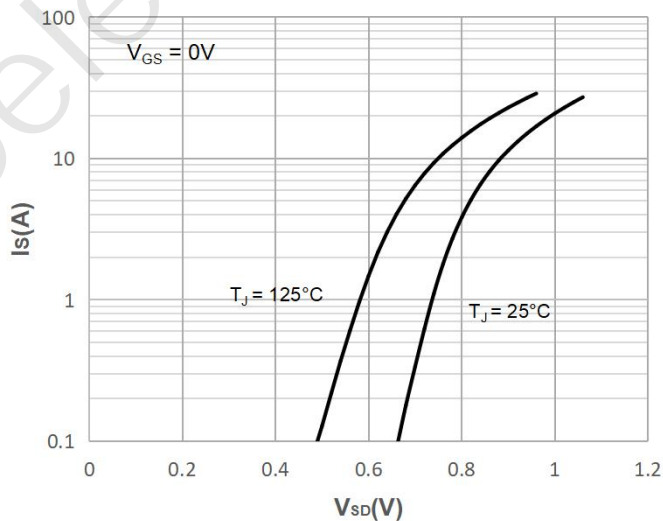


Figure 5: Gate Charge Characteristics

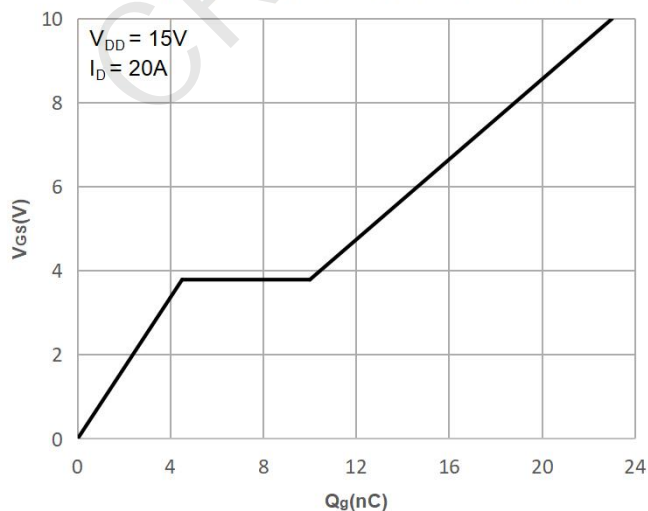
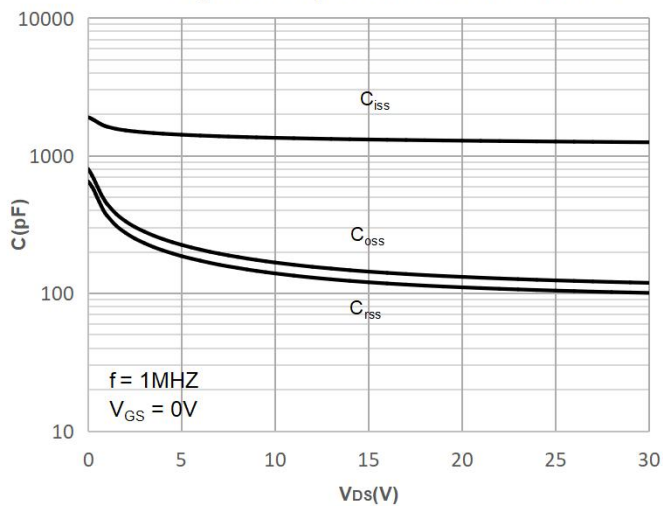


Figure 6: Capacitance Characteristics



Typical Performance Characteristics

Figure 7: Normalized Breakdown voltage vs. Junction Temperature

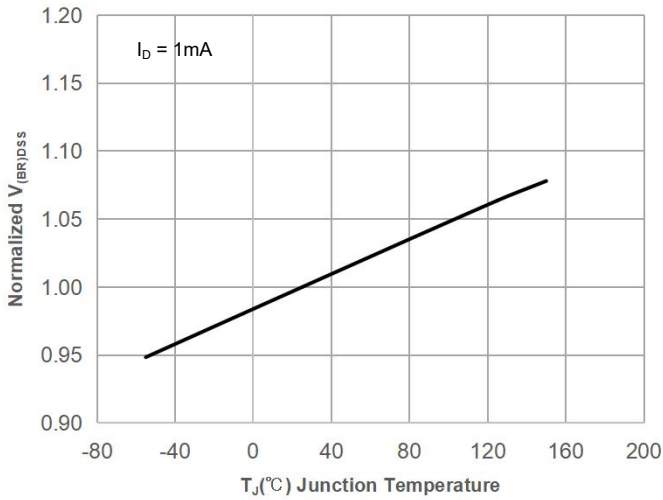


Figure 8: Normalized on Resistance vs. Junction Temperature

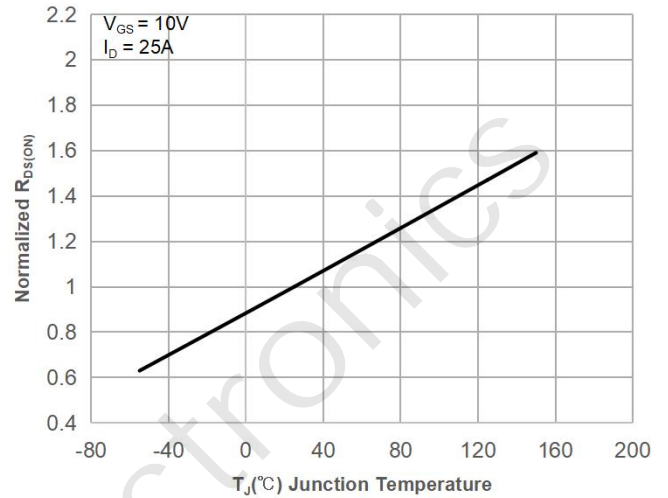


Figure 9: Maximum Safe Operating Area

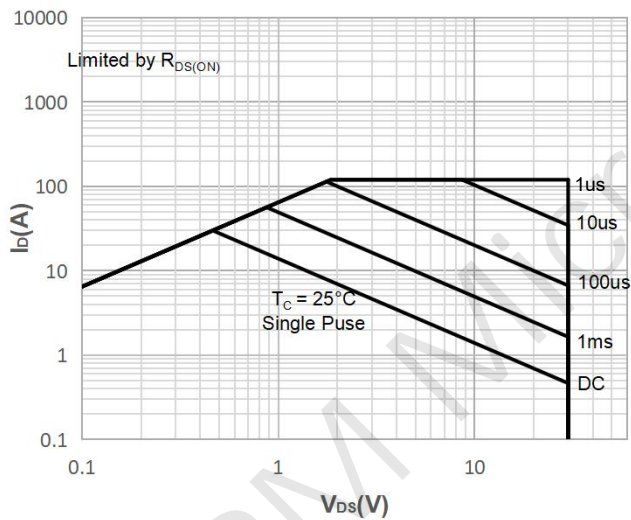


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

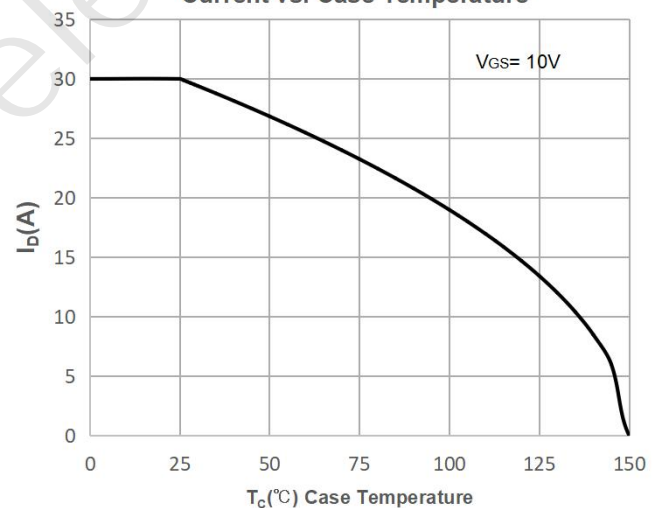


Figure 11: Normalized Maximum Transient Thermal Impedance

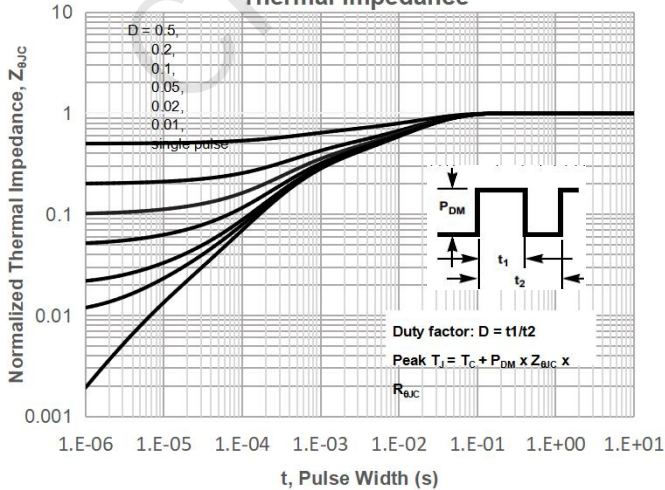
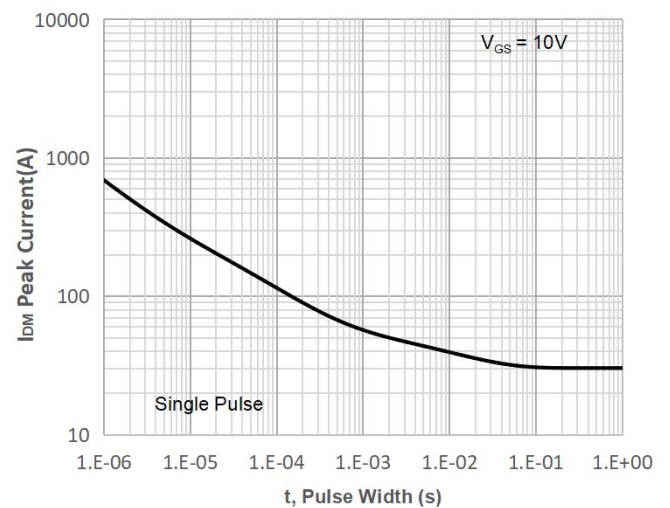


Figure 12: Peak Current Capacity



Test Circuit

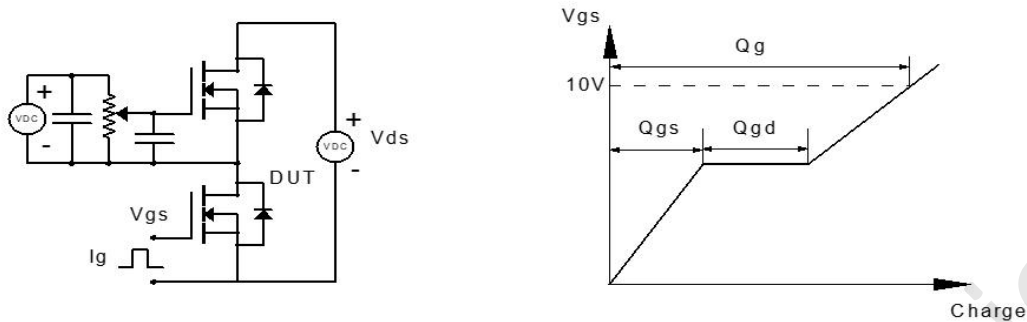


Figure 1: Gate Charge Test Circuit & Waveform

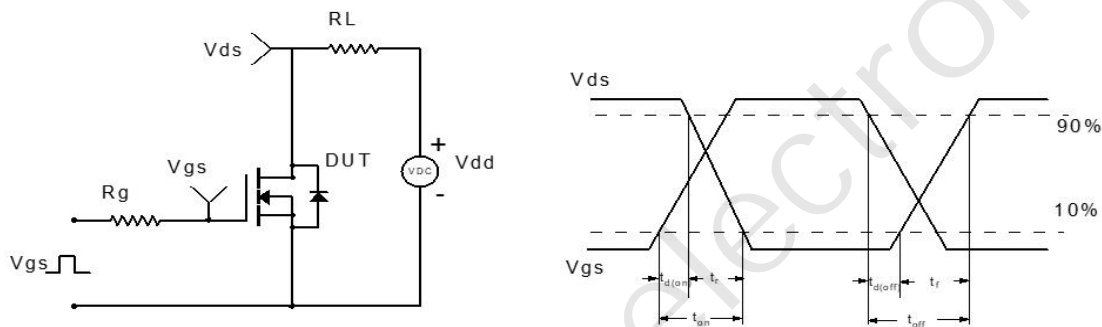


Figure 2: Resistive Switching Test Circuit & Waveform

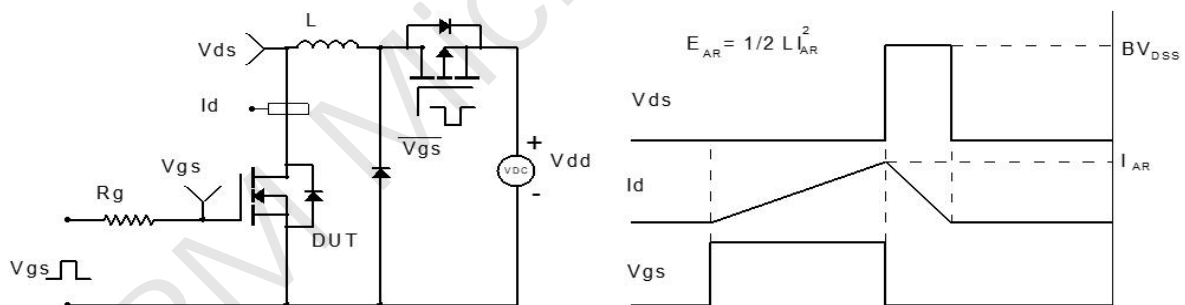


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

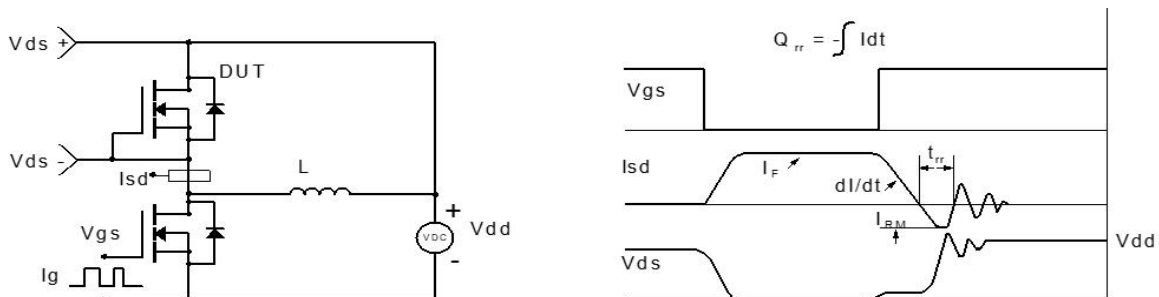
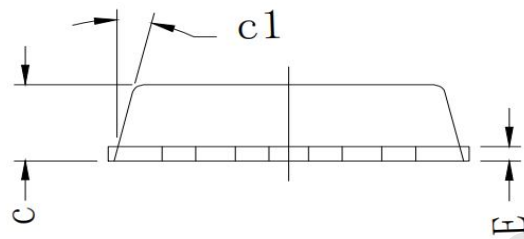
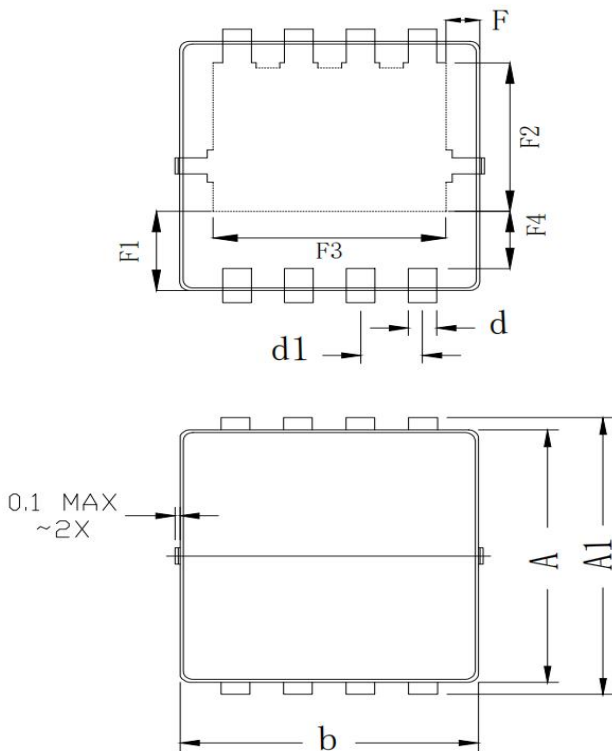


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(PDFN3.3x3.3-8L)




COMMON DIMENSION (MM)			
PKG	PDFN 3.3×3.3-8L		
SYMBOL	MIN	TYP	MAX
A	3.070	3.100	3.130
A1	3.300	3.400	3.500
b	3.070	3.100	3.130
c	0.770	0.800	0.830
c1	—	13°	—
d	0.275	0.300	0.325
d1	0.625	0.650	0.675
E	0.144	0.152	0.160
F	0.300	0.325	0.350
F1	0.960	0.985	1.010
F2	1.775	1.800	1.825
F3	2.425	2.450	2.475
F4	0.660	0.685	0.710

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